



CRITICAL LINE WIDTH = .016 ± .001 ADJUST PROCESS TO ACHIEVE WIDTH

TABLE 1: HOLE DIAMETERS

LETTER DESIG.	DIAMETER	QTY	TYPE	NOTES
NONE	0.010	5	PTH	± .003
NONE	0.018	66	PTH	± .003
NONE	0.043	2	PTH	± .003

UNLESS OTHERWISE SPECIFIED:	
DIMENSIONS ARE IN INCHES (MM)	
DRAWING PRACTICES PER MIL-STD-100	
TOLERANCES:	
.XX	+/- .01
.XXX	+/- .005
ANGLES	+/- .5 DEG

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

DRAWN	DMF 08/31/05
CHECKED	
ENG. APPD.	
HMC APPD.	
RELEASED	



HITTITE MICROWAVE CORPORATION  
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Chelmsford, MA 01824

TITLE  
PCB, EVAL  
HMC448/449LC3B

SIZE	CODE ID NO.	DRAWING NO.	REV
A	1CN88	112841	1
SCALE	2.5TD 1	WT	SHEET 1 OF 1

REVISION			
ZONE	REV	DESCRIPTION	DATE
	1	ENGINEERING RELEASE	08/31/05
			DMF

MET-1	1/2 OZ COPPER	
	0.010" ± 0.001 ROGERS 4350	
	SEE NOTE# 1	
MET-2	1/2 OZ COPPER	
	PREPRAG AS REQUIRED	
MET-3	1/2 OZ COPPER	
	.028" FR4	
	SEE NOTE# 1	
MET-4	1/2 OZ COPPER	

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350, HALF OUNCE COPPER BOTH SIDES.
2. FINISH: GOLD PLATE PER MIL-G-45204, TYPE III, GRADE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 50 TO 100 MICROINCHES.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ±.003" OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ±.003" MAX
7. BOARD WARPAGE: .010" PER LINEAR INCH MAX
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK
9. TOLERANCE ON PCB ROUTE IS ±.005"
10. PLATING THICKNESS .0018" ± .0005 FOR MET-1 AND MET-4
11. SOLDERMASK: LPI SOLDERMASK TOPSIDE ONLY. COLOR: GREEN REGISTRATION: ±.004 MAX  
\*\*\* APPLY SOLDERMASK AS DESIGNED. ANY ALTERATIONS OF SOLDERMASK MUST FIRST BE APPROVED BY HITTITE MICROWAVE.
12. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPERATION.
13. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
14. EDGE PLATING MUST CONNECT ALL 4 METAL LAYERS.